

## N-channel 60 V, 4.2 mΩ typ., 80 A STripFET™ F7 Power MOSFET in a D<sup>2</sup>PAK package

Datasheet - production data

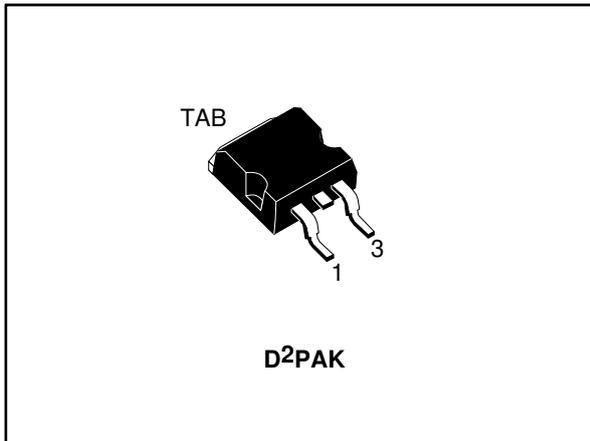


Figure 1: Internal schematic diagram

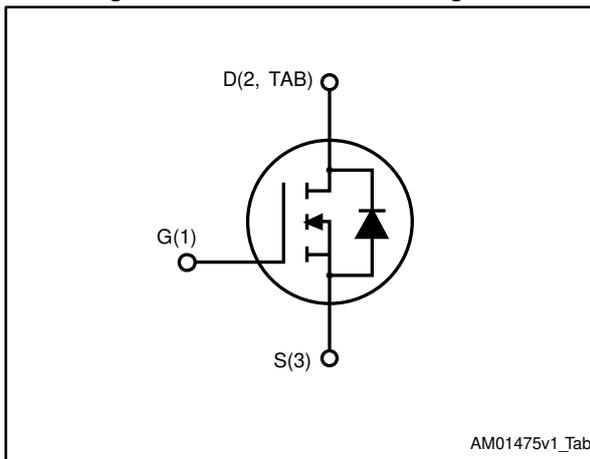


Table 1: Device summary

Order code	Marking	Package	Packing
STB130N6F7	130N6F7	D <sup>2</sup> PAK	Tape and reel

### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	P <sub>TOT</sub>
STB130N6F7	60 V	5.0 mΩ	80 A	160 W

- Among the lowest R<sub>DS(on)</sub> on the market
- Excellent figure of merit (FoM)
- Low C<sub>rss</sub>/C<sub>iss</sub> ratio for EMI immunity
- High avalanche ruggedness

### Applications

- Switching applications

### Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

---

## Contents

<b>1</b>	<b>Electrical ratings .....</b>	<b>3</b>
<b>2</b>	<b>Electrical characteristics .....</b>	<b>4</b>
	2.1 Electrical characteristics (curves).....	5
<b>3</b>	<b>Test circuits .....</b>	<b>7</b>
<b>4</b>	<b>Package information .....</b>	<b>8</b>
	4.1 D <sup>2</sup> PAK type A package information.....	8
	4.2 D <sup>2</sup> PAK packing information .....	11
<b>5</b>	<b>Revision history .....</b>	<b>13</b>

# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	60	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_{case} = 25\text{ }^\circ\text{C}$	80	A
	Drain current (continuous) at $T_{case} = 100\text{ }^\circ\text{C}$	80	
$I_{DM}^{(2)}$	Drain current (pulsed)	320	A
$P_{TOT}$	Total dissipation at $T_{case} = 25\text{ }^\circ\text{C}$	160	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	200	mJ
$T_{stg}$	Storage temperature	-55 to 175	$^\circ\text{C}$
$T_j$	Operating junction temperature		

**Notes:**

- (1) Current is limited by package.  
 (2) Pulse width is limited by safe operating area.  
 (3) starting  $T_j = 25\text{ }^\circ\text{C}$ ,  $I_D = 20\text{ A}$ ,  $V_{DD} = 40\text{ V}$ .

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.94	$^\circ\text{C/W}$
$R_{thj-amb}^{(1)}$	Thermal resistance junction-ambient	30	

**Notes:**

- (1) When mounted on a 1-inch<sup>2</sup> FR-4, 2 Oz copper board.

## 2 Electrical characteristics

( $T_{\text{case}} = 25\text{ °C}$  unless otherwise specified)

**Table 4: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	60			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 60\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 40\text{ A}$		4.2	5.0	$\text{m}\Omega$

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	2600	-	pF
$C_{oss}$	Output capacitance		-	1200	-	
$C_{riss}$	Reverse transfer capacitance		-	115	-	
$Q_g$	Total gate charge	$V_{DD} = 30\text{ V}$ , $I_D = 80\text{ A}$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 14: "Gate charge test circuit"</a> )	-	42	-	nC
$Q_{gs}$	Gate-source charge		-	13.6	-	
$Q_{gd}$	Gate-drain charge		-	13	-	

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30\text{ V}$ , $I_D = 40\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 13: "Switching times test circuit for resistive load"</a> and <a href="#">Figure 18: "Switching time waveform"</a> )	-	24	-	ns
$t_r$	Rise time		-	44	-	
$t_{d(off)}$	Turn-off delay time		-	62	-	
$t_f$	Fall time		-	24	-	

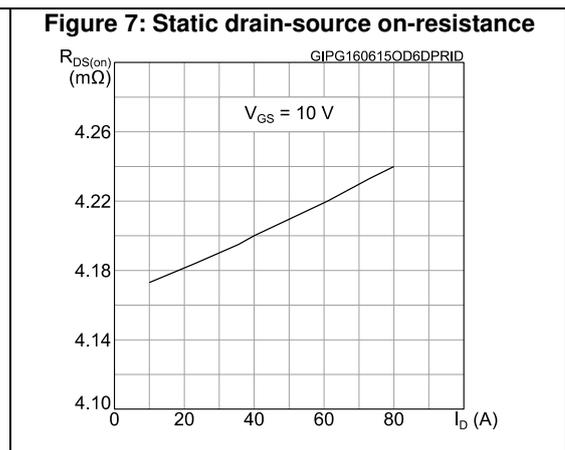
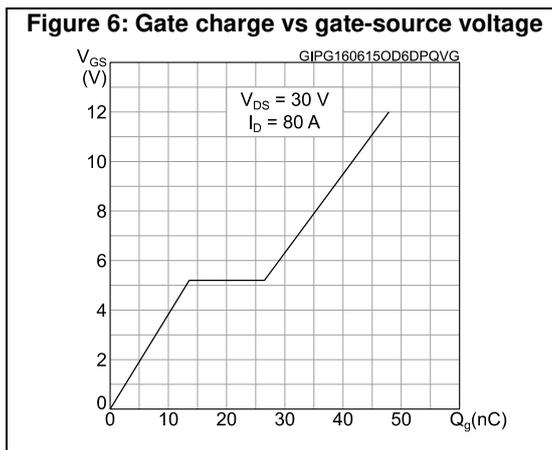
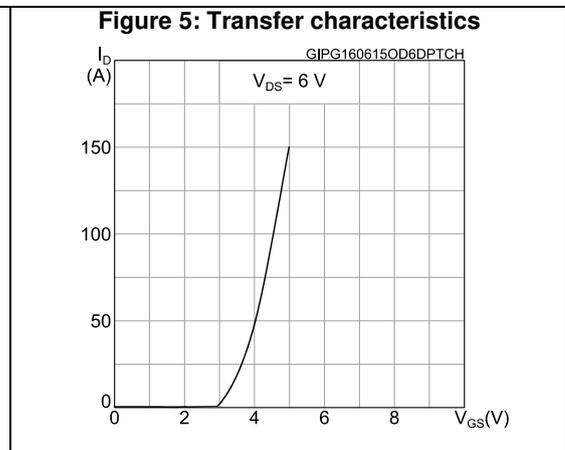
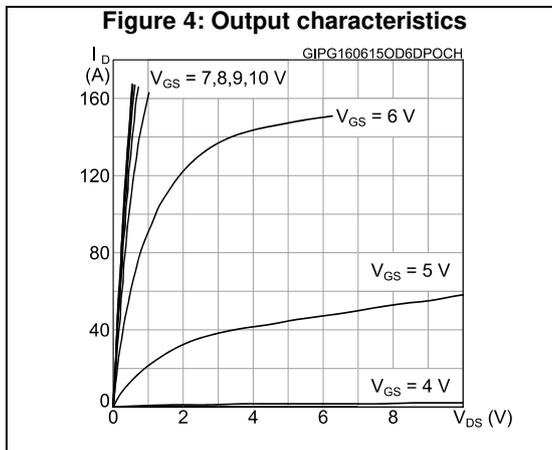
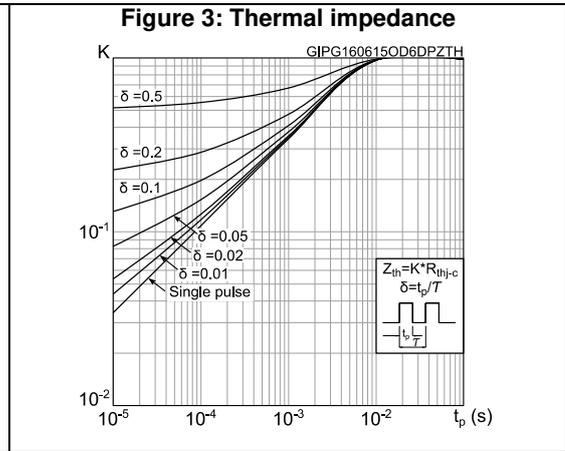
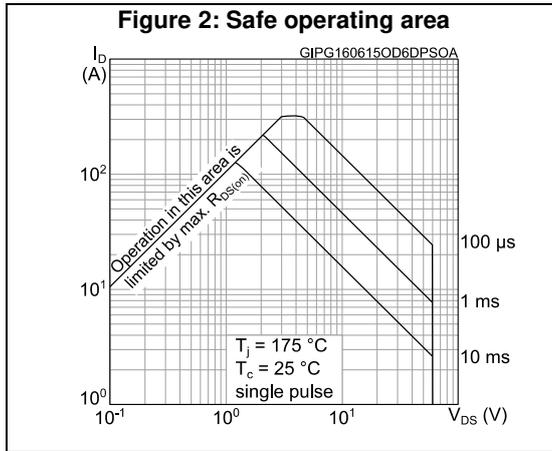
**Table 7: Source-drain diode**

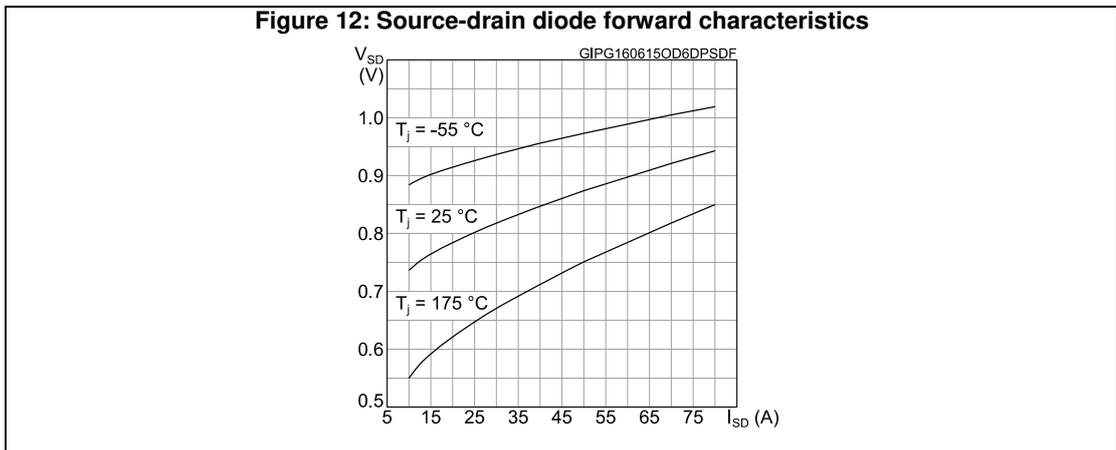
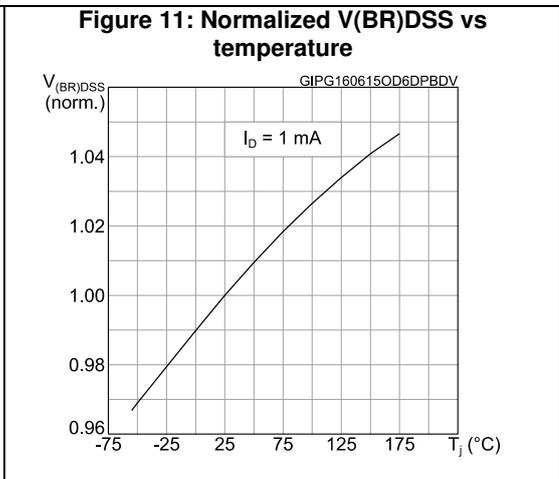
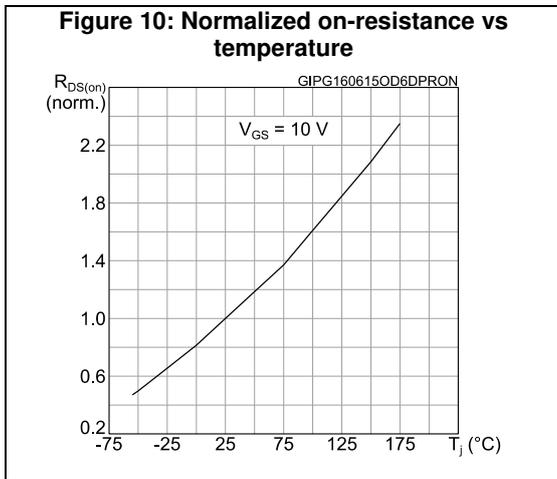
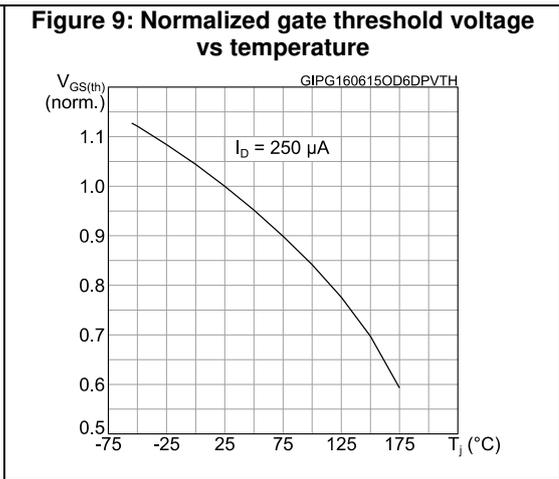
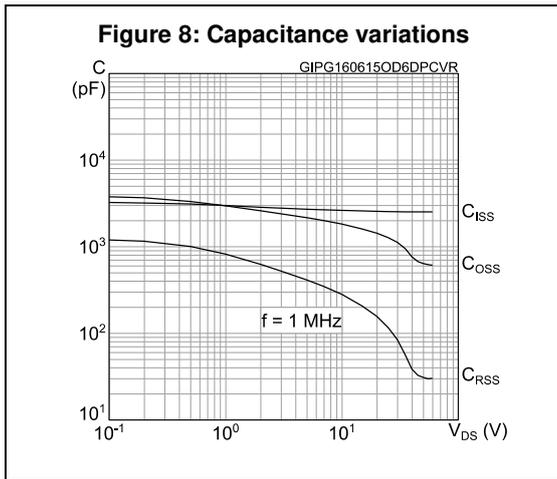
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 80\text{ A}$	-		1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 80\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 48\text{ V}$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> )	-	50		ns
$Q_{rr}$	Reverse recovery charge		-	56		nC
$I_{RRM}$	Reverse recovery current		-	2.2		A

**Notes:**

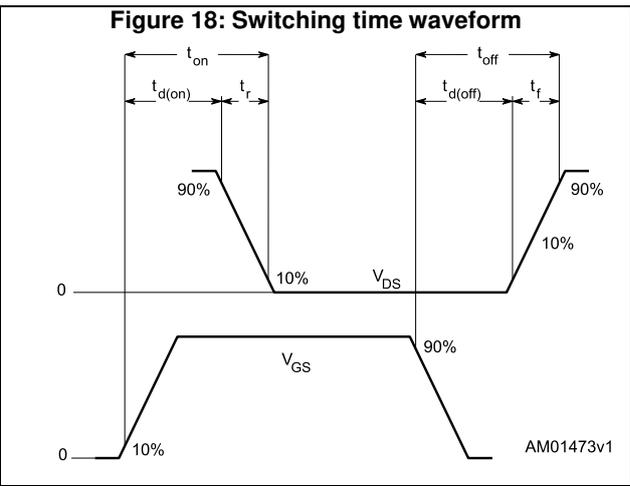
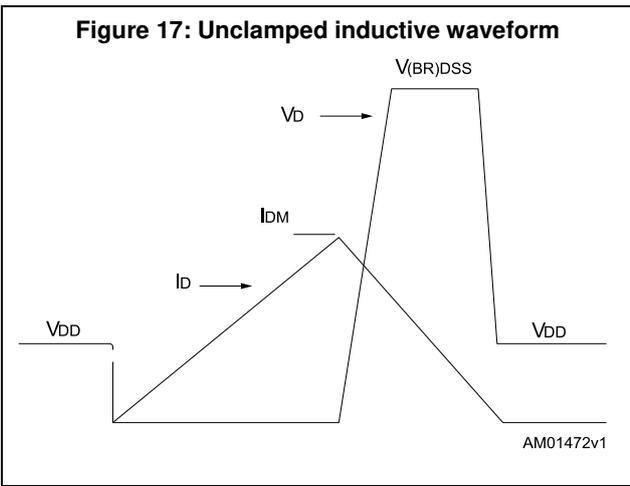
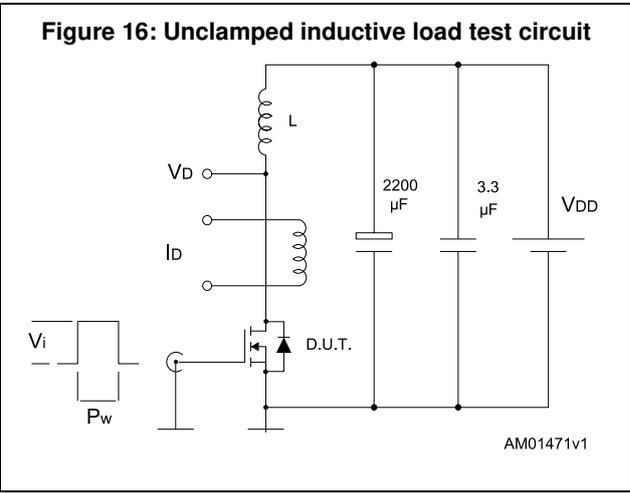
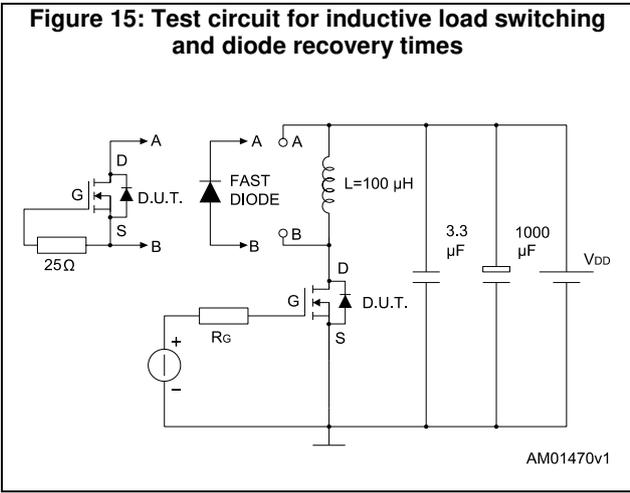
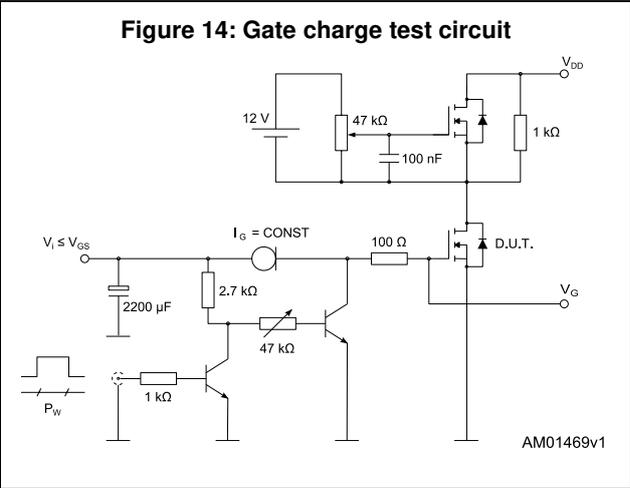
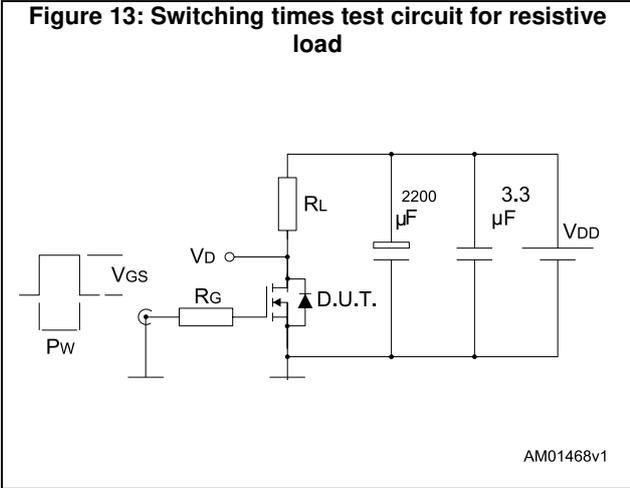
<sup>(1)</sup> Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)





### 3 Test circuits



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 D<sup>2</sup>PAK type A package information

Figure 19: D<sup>2</sup>PAK (TO-263) type A package outline

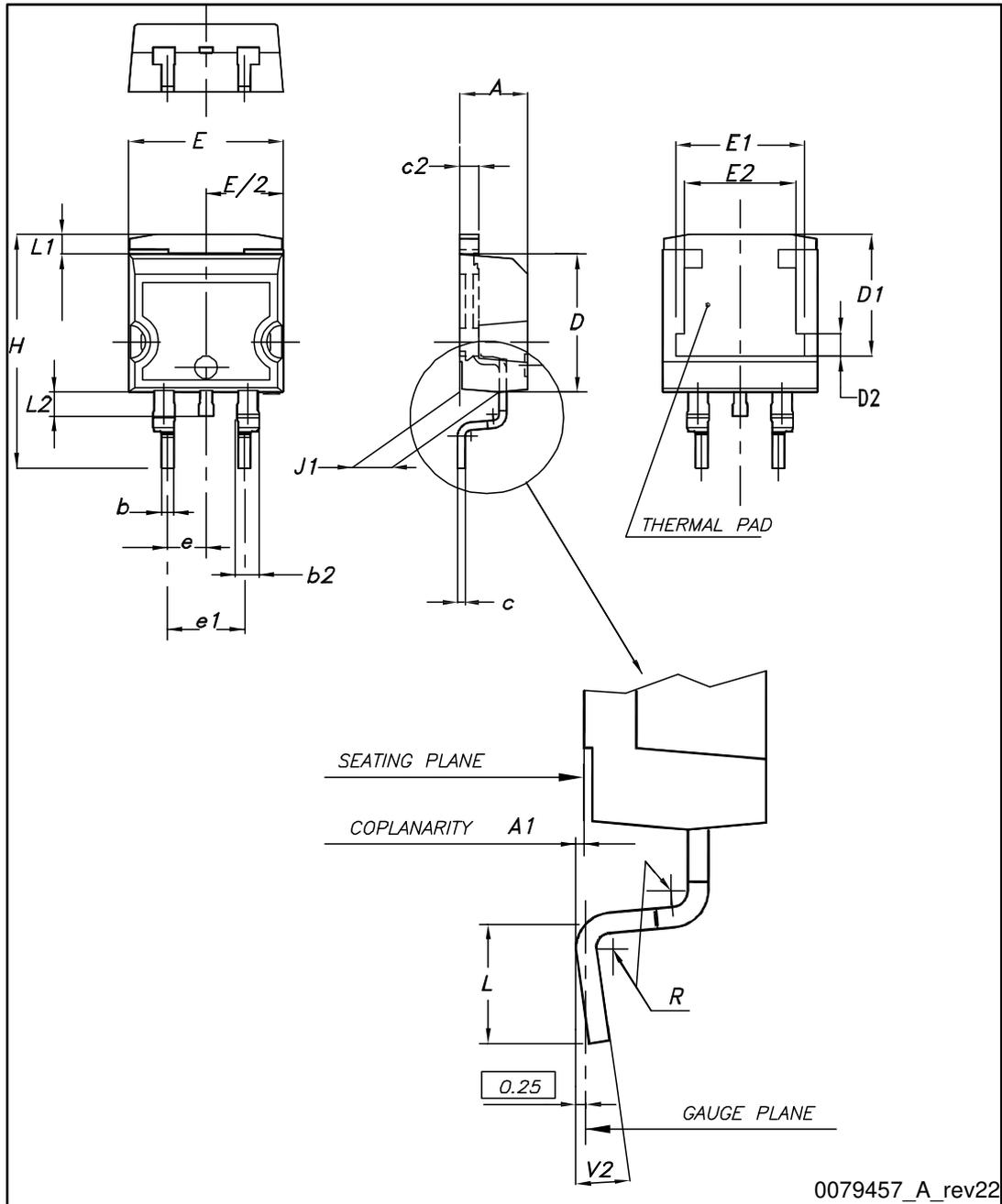
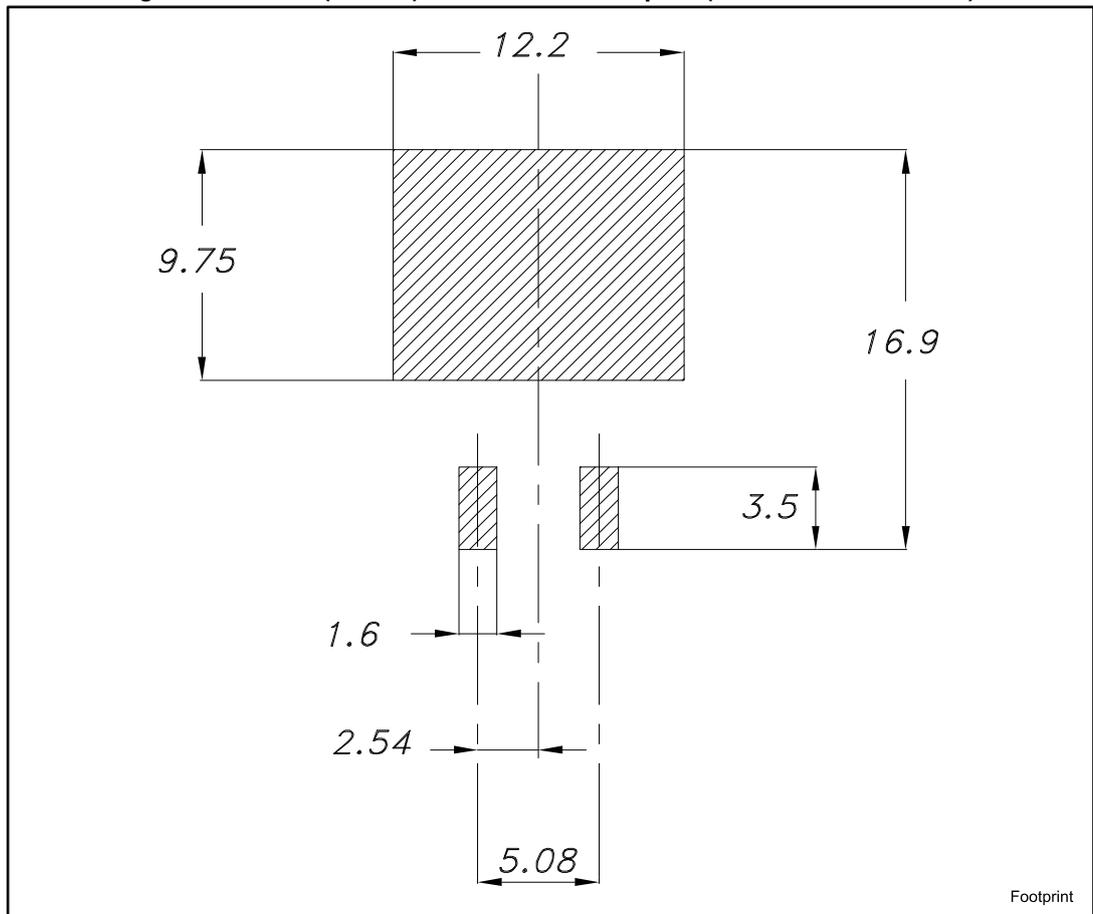


Table 8: D<sup>2</sup>PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 20: D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)



Footprint

### 4.2 D<sup>2</sup>PAK packing information

Figure 21: Tape

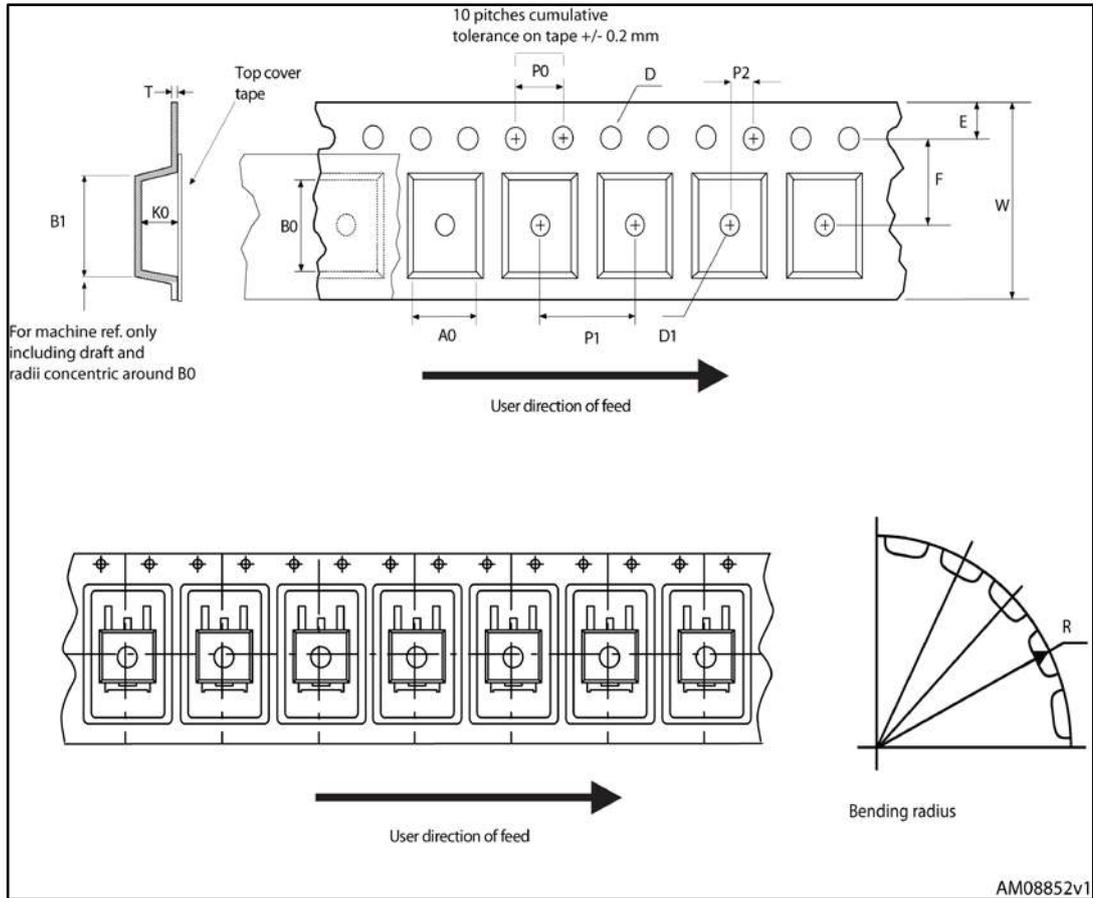


Figure 22: Reel

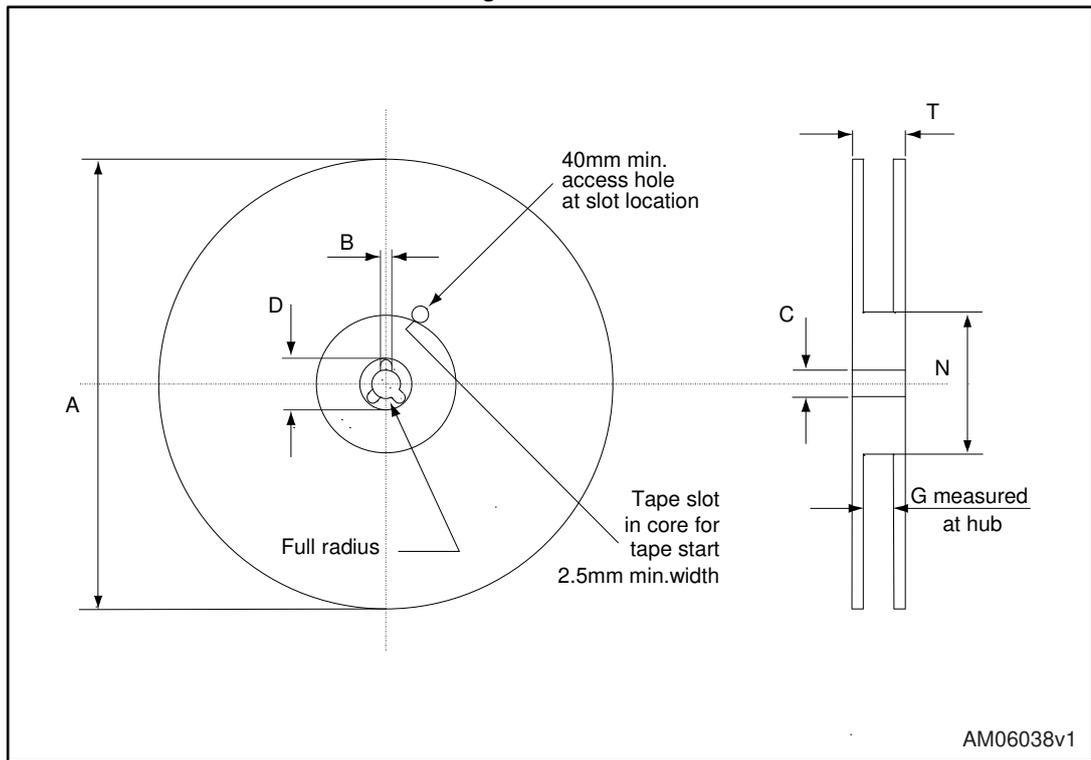


Table 9: D<sup>2</sup>PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
23-Jan-2015	1	First release.
16-Jun-2015	2	Datasheet promoted from preliminary data to production data Text and formatting edits throughout document In Section Electrical ratings: - updated Table Absolute maximum ratings In Section Electrical characteristics: - updated and renamed Table Static (was On/off states) - updated Table Switching times - updated Table Source drain diode Added Section Electrical characteristics (curves)
08-Jul-2015	3	In Section <i>Electrical characteristics (curves)</i> : - updated Figures <i>Output characteristics</i> and <i>Transfer characteristics</i>

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2015 STMicroelectronics – All rights reserved